



Morphology and Electrochemistry Drive Corrosion of Electroless Nickel Immersion Gold Films: A Multi-Technique Analysis



PRESENTED BY

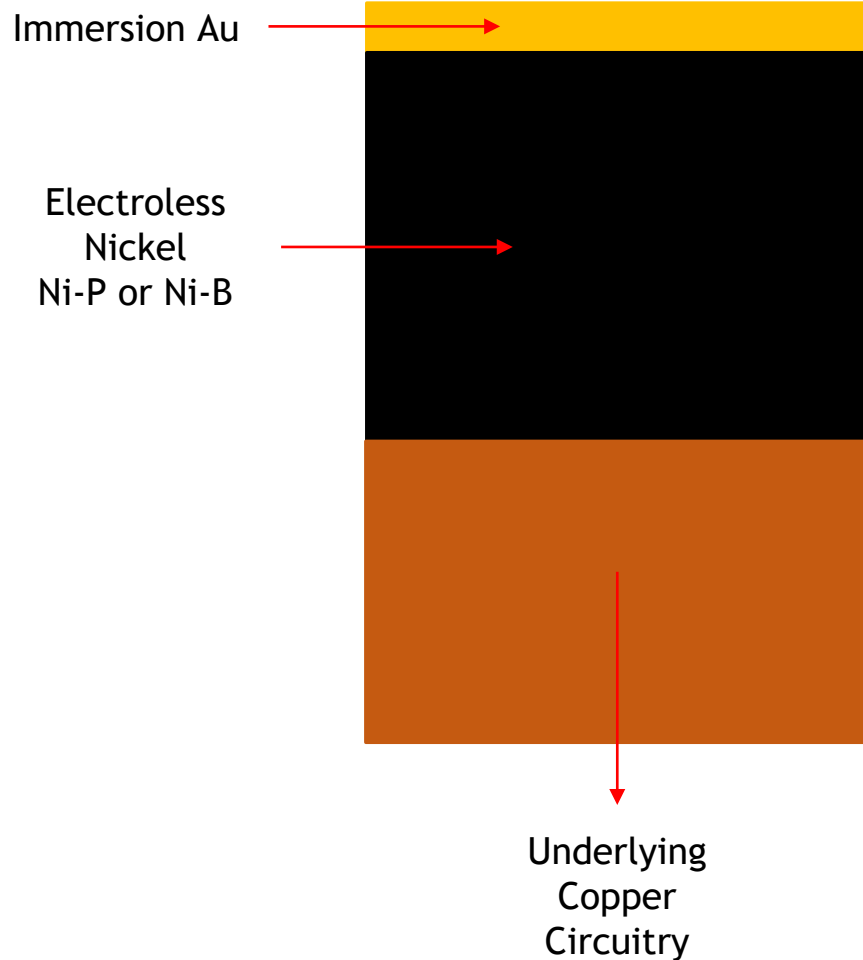
Elliott Fowler, Sandia National Labs (NM)

Team –

Samantha G. Rosenberg, Jessica Faubel, Melissa Meyerson (SNL), Rupesh Rajendran, Jahnavi Desai Choundraj, Josh Kacher, Preet Singh (Georgia Tech.)

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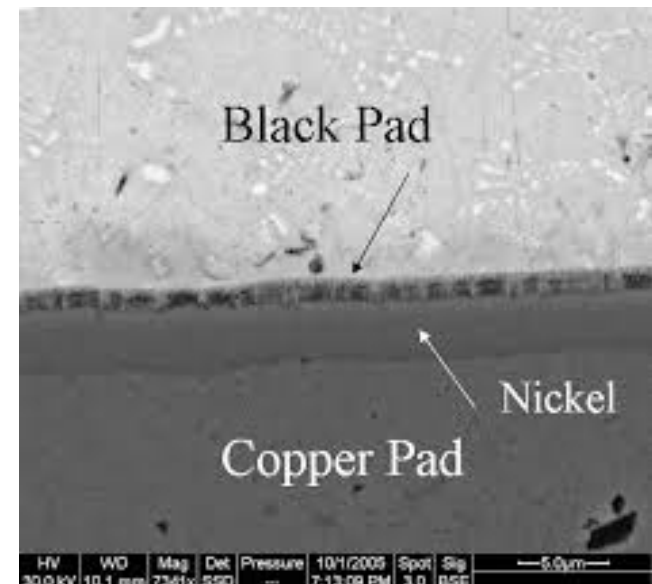
Electroless Nickel Immersion Gold (ENIG)



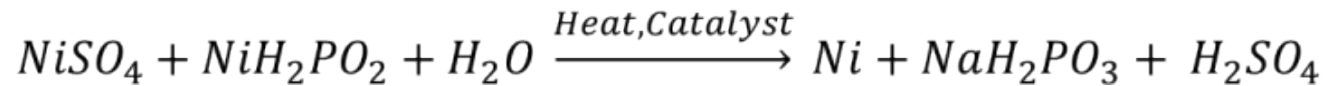
Enhance solderability to copper pads

Minimize oxidation of base Cu layer

“Black Pad” phenomenon not well explained in literature



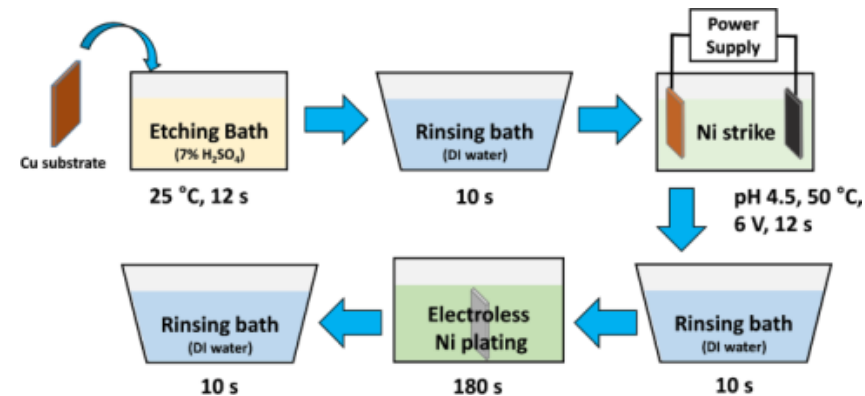
Pecht et al 2008
doi:10.1016/j.microrel.2008.02.003



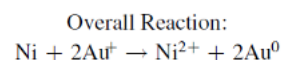
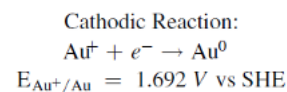
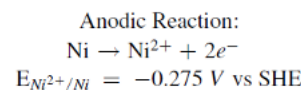
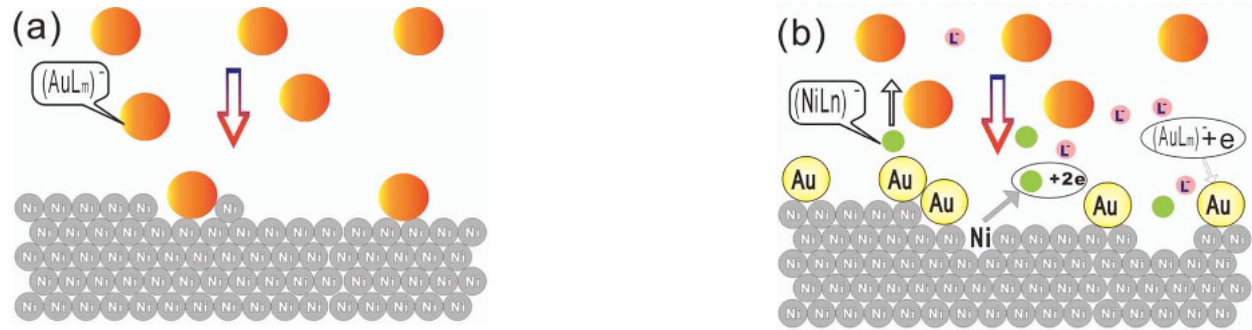
Process Inputs

Metal salt concentration
Additive 1 concentration
Additive 2 concentration
pH
Temperature
Current density
Agitation

1) Electroless Nickel



2) Immersion Gold



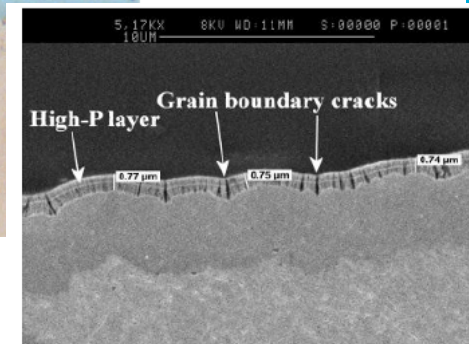
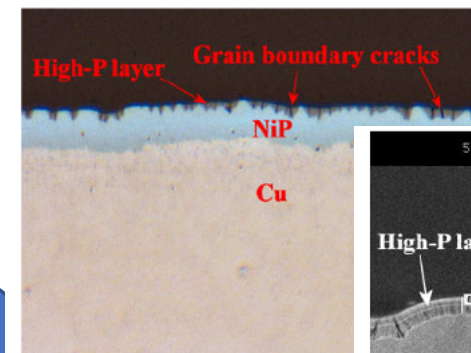
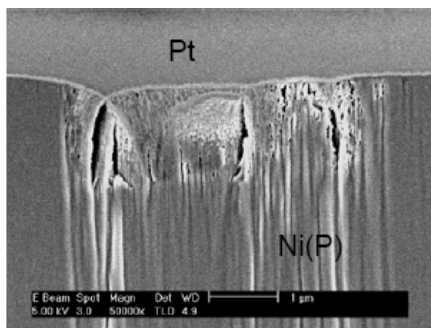
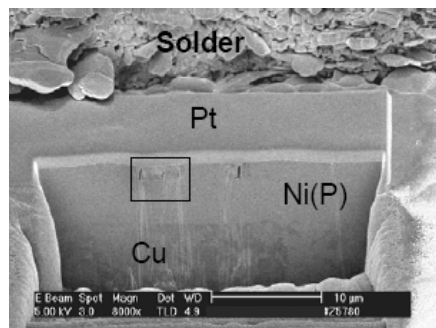
Liu *et al* 2007

<https://doi.org/10.1149/1.2790281>

Let's Agree to Disagree on the Root Cause(s)



Too Much (or Too Little) Phos.

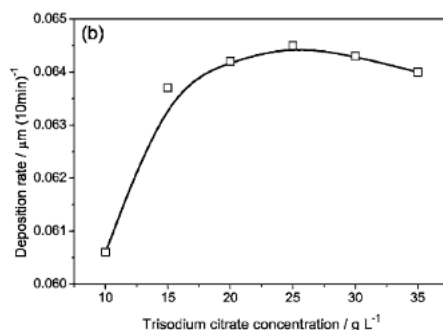
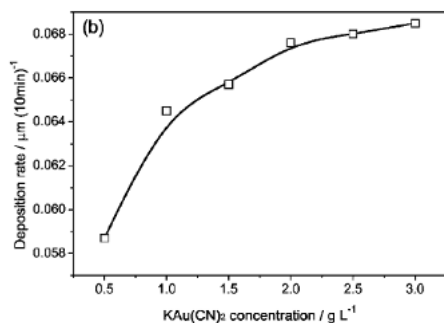


Galvanic Hyper-Corrosion of Ni(P)

Zeng *et al* 2006

<https://doi.org/10.1109/ITHERM.2006.1645469>

Potential
Root Causes

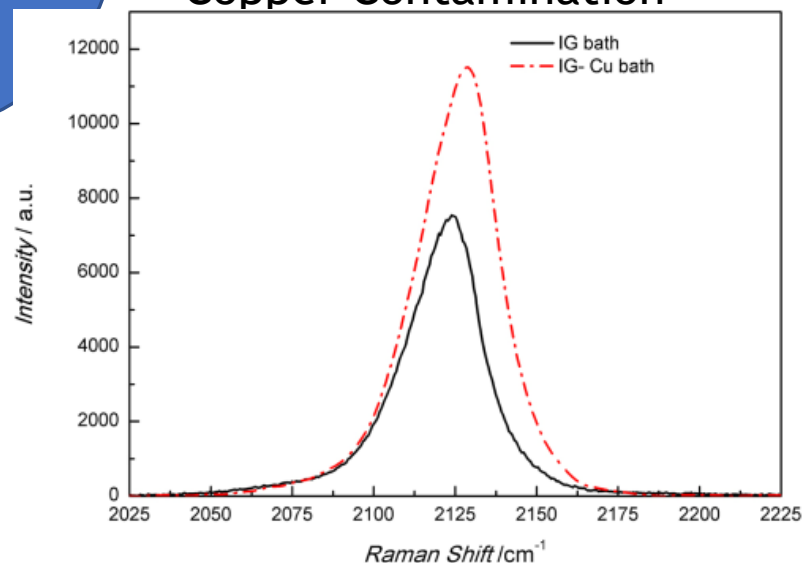


Additives and Complexing Agents

Liu *et al* 2007

<https://doi.org/10.1149/1.2790281>

Copper Contamination

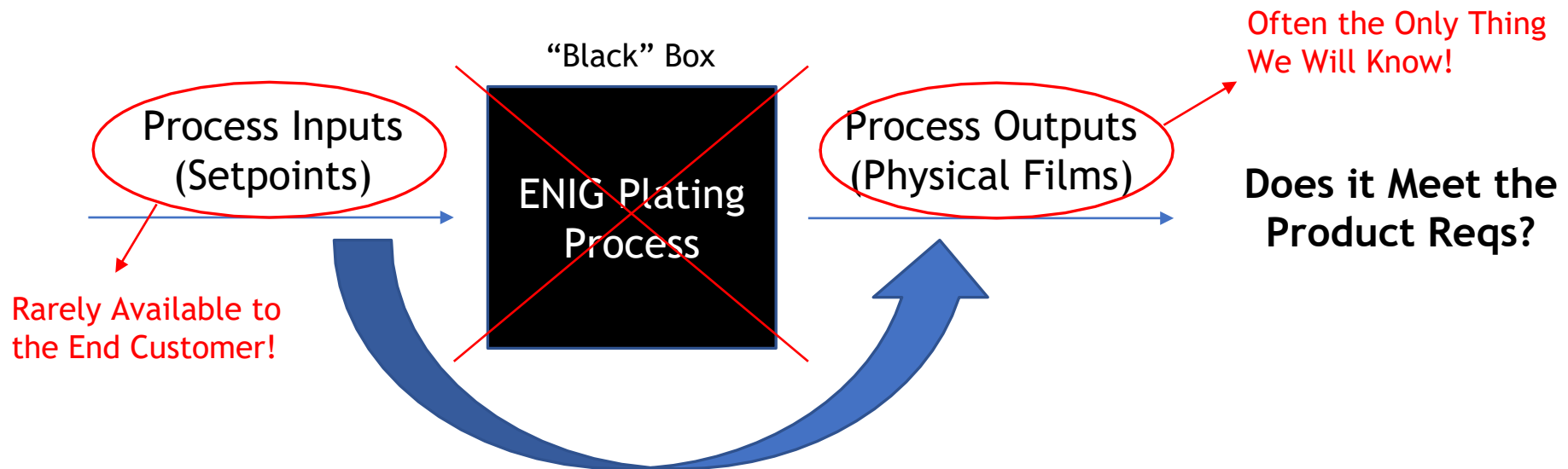


Accogli *et. al* 2022

<https://doi.org/10.1149/1945-7111/ab8ce6>



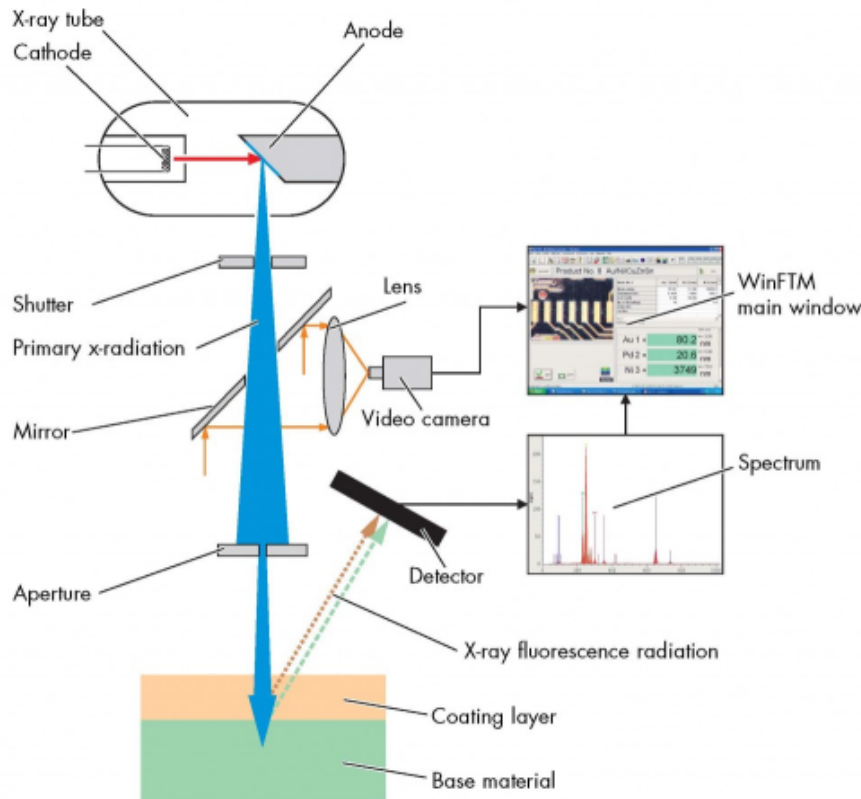
In-Situ Diagnosis of the Root Cause of Poor ENIG Plating is a High-Complexity, Low Reward Effort



Can We Develop Methodologies to Distinguish Amongst These Potential Failure Modes Without the Luxury of Peeking Into the Black Box?

How is ENIG (Post)Characterized Now?

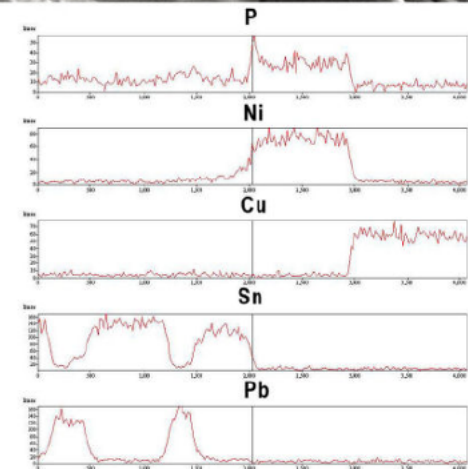
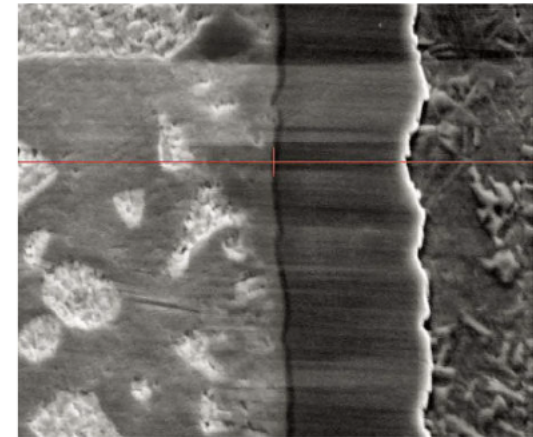
X-Ray Fluorescence (XRF) Spectroscopy



Chemical speciation, some structural information



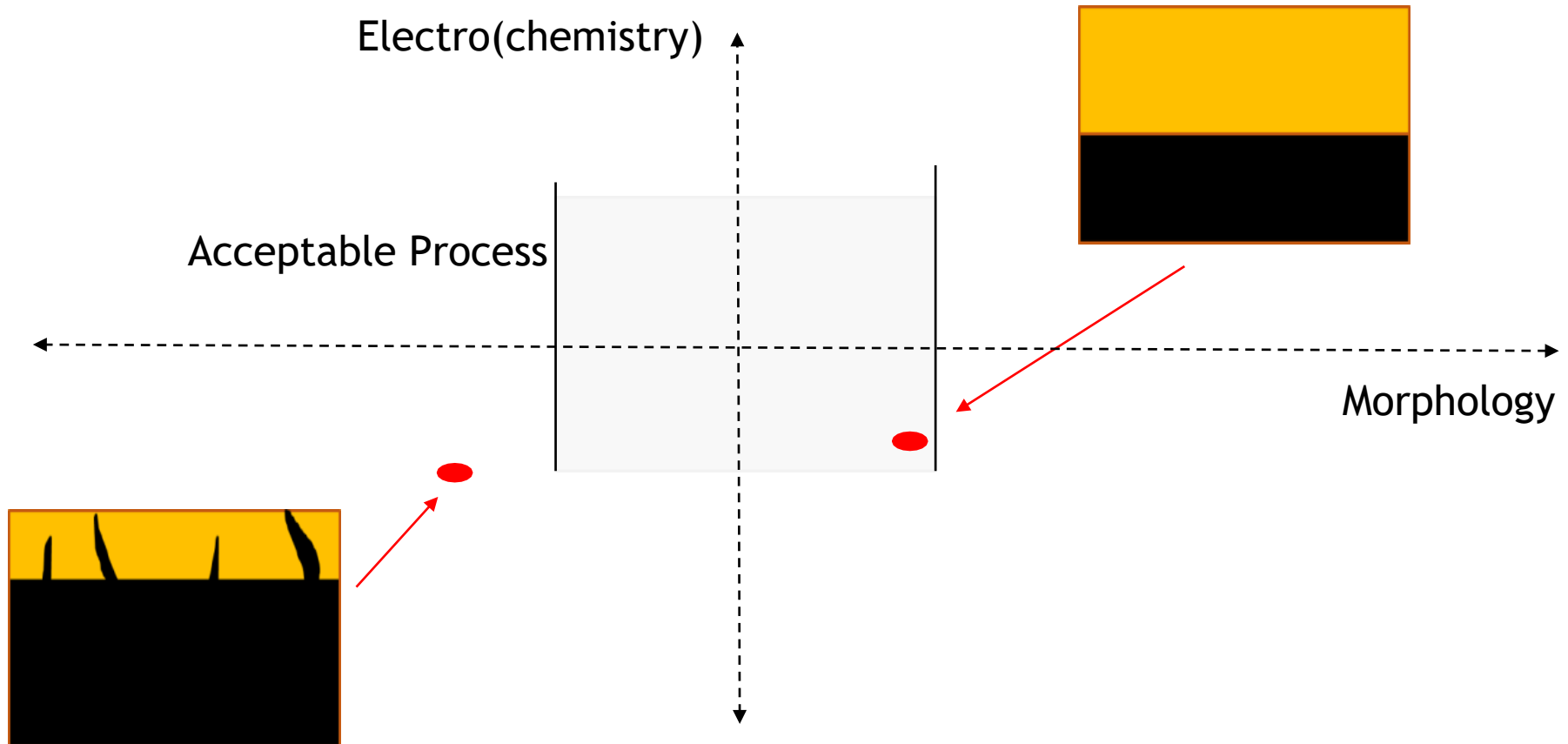
FIB Section and SEM/EDS



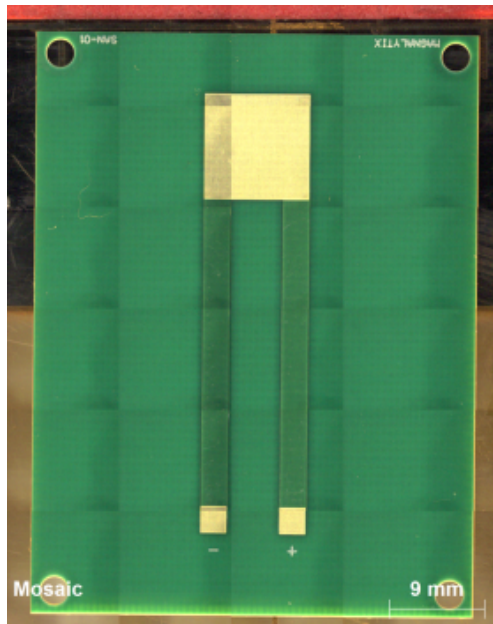
Low-quality chemical speciation, high-quality structural information



Electro(chemistry) and Morphology Dictate Whether ENIG Films Meet Performance Requirements



Insights Into **Both** the **Electro(chemistry)** and **Morphology** of an ENIG Film Are Necessary to Properly Classify Whether Process -> Performance



Electro(chemistry)

Morphology

Cyclic Polarization

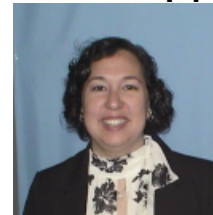
SEM/STEM

Preet Singh
Georgia Tech.

SVET



XPS Depth
Profiling



Samantha Rosenberg
Sandia Nat'l Labs

Josh Kacher
Georgia Tech.

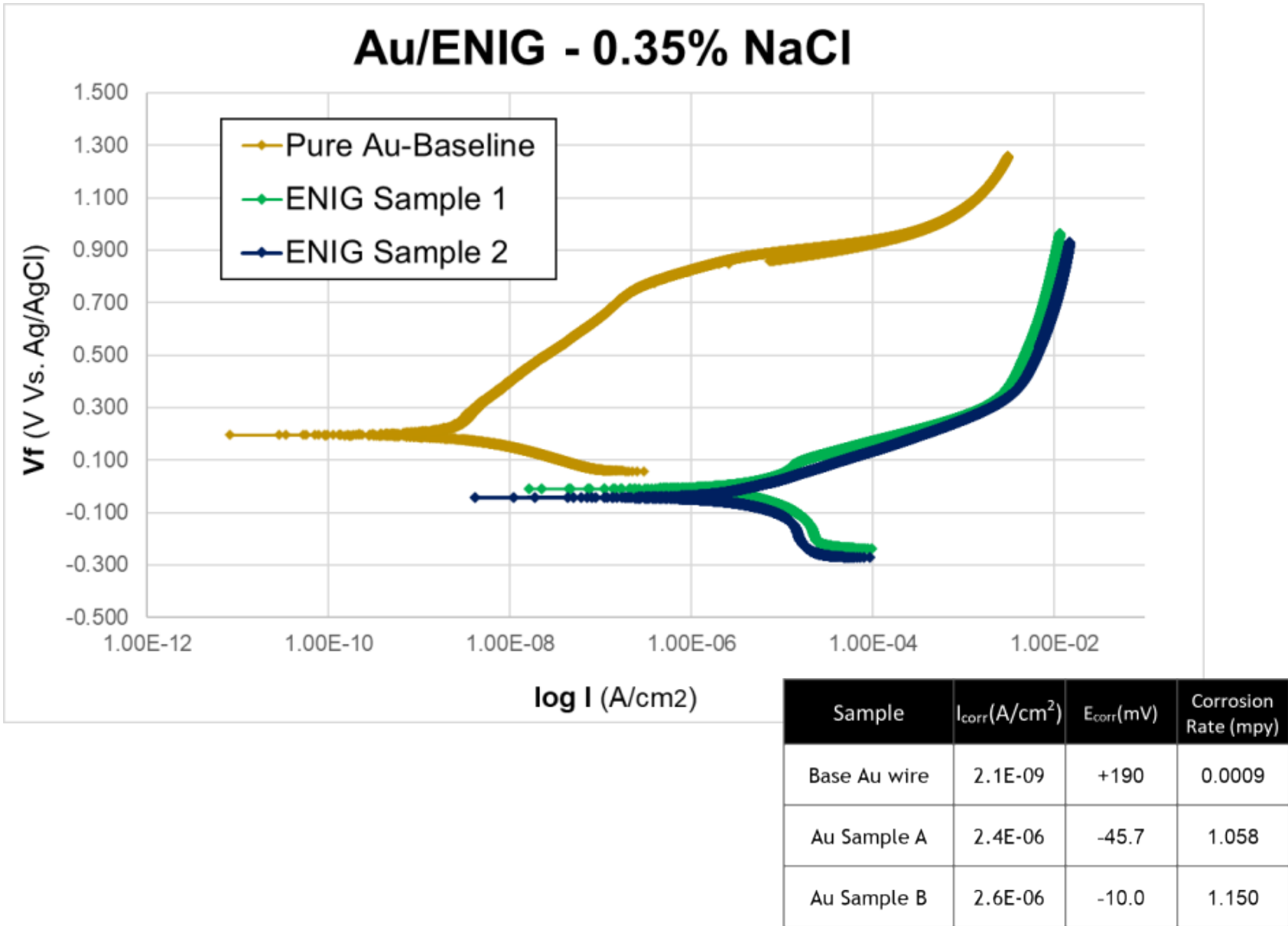


Specified
Reqs

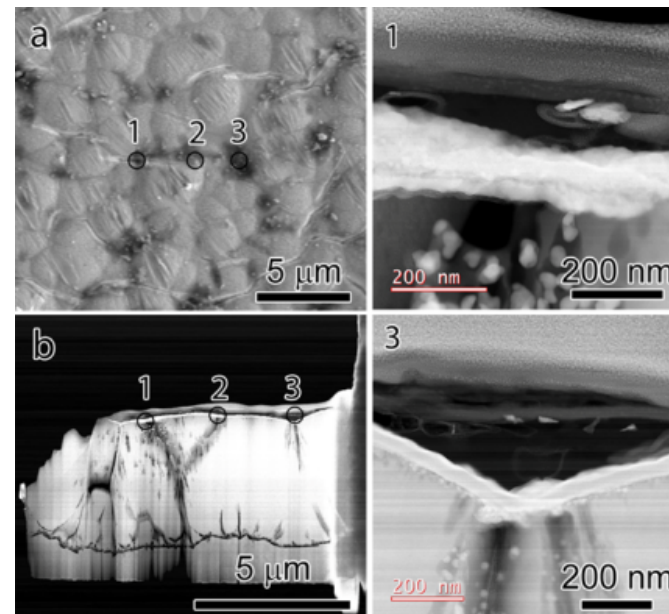
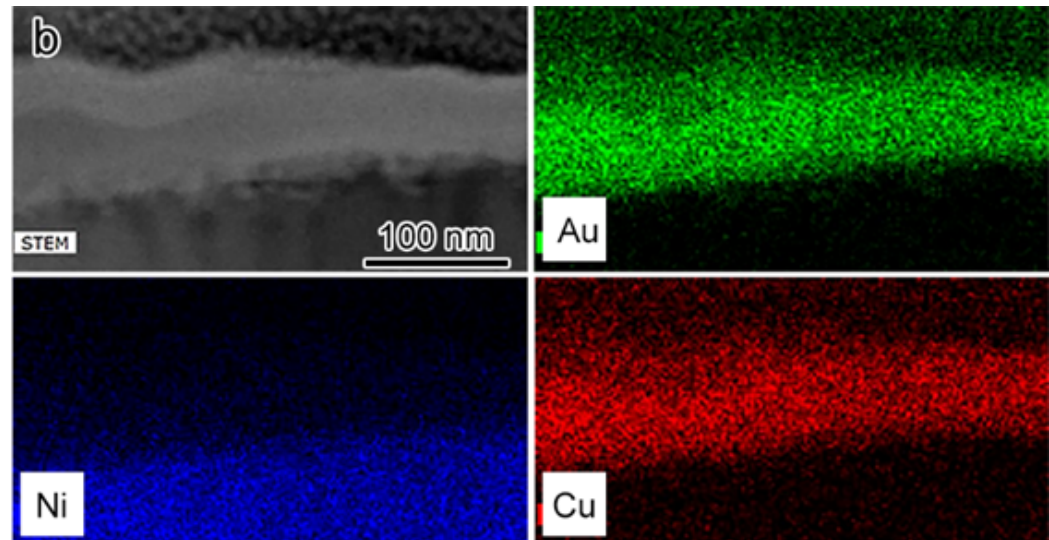
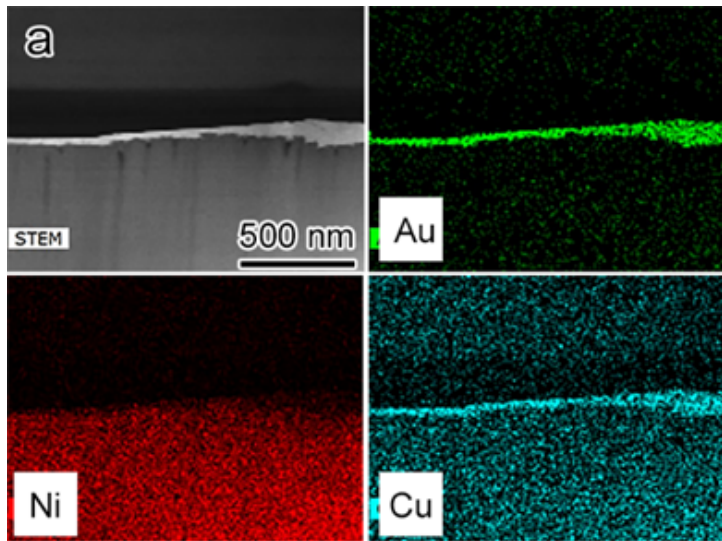
Black Box
EP Process

“Vendor A”

“Vendor B”



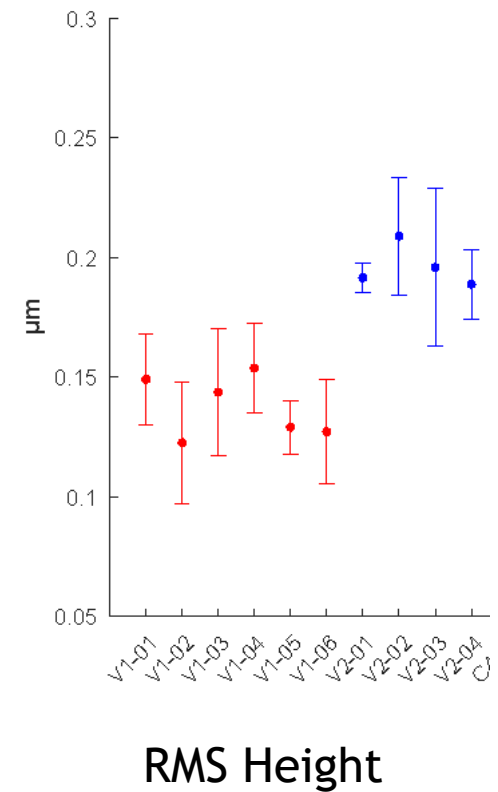
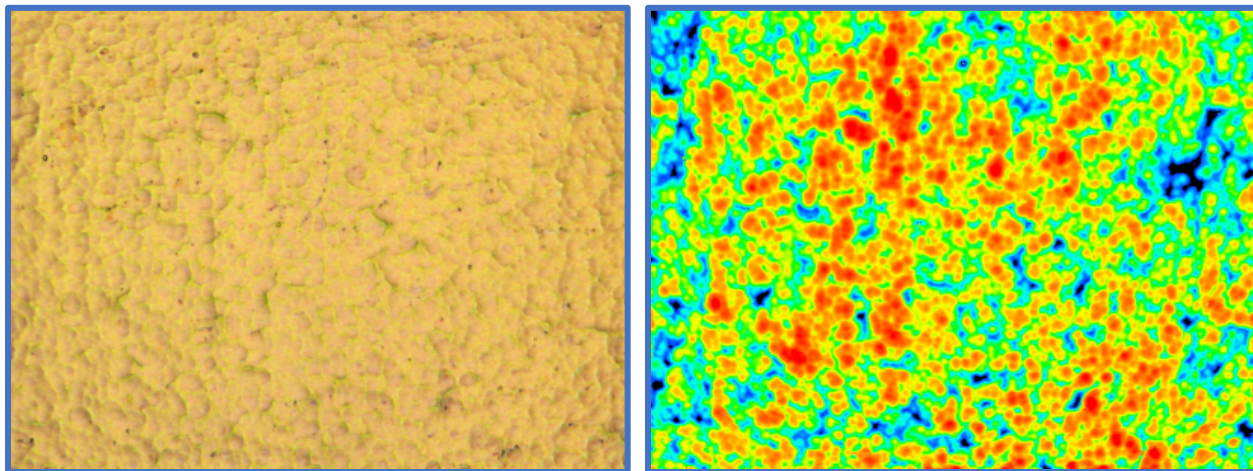
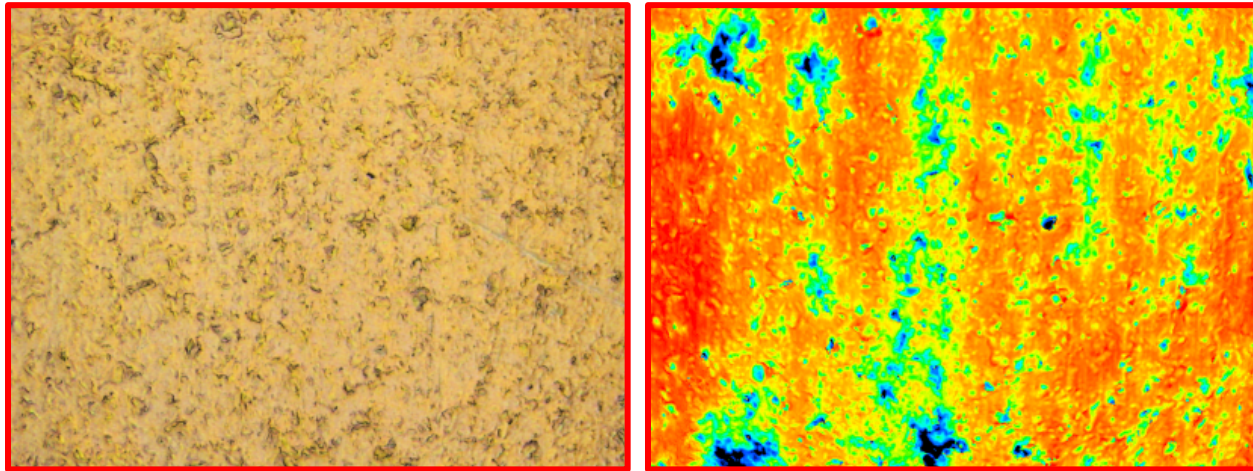
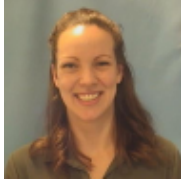
Results (Scanning/Transmission Electron Microscopies)



Was noted that one Vendor's samples appeared rougher than the other..



Jessica Faubel
Sandia Nat'l Labs



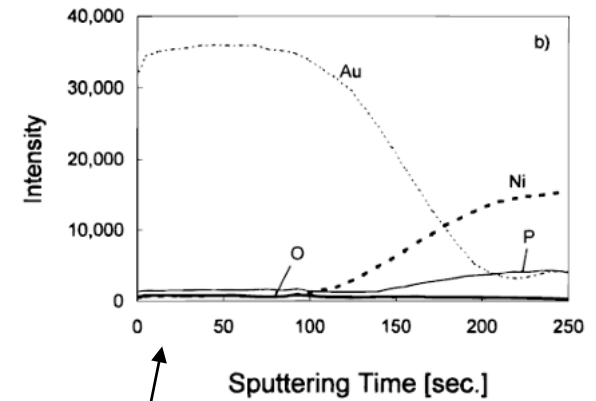
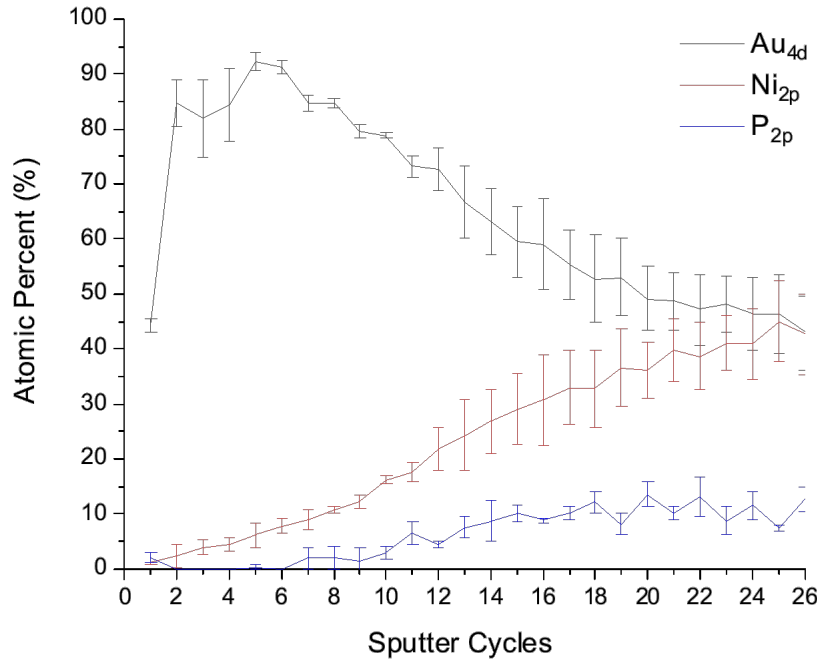
272 μm

Results (X-Ray Photoelectron Spectroscopy)

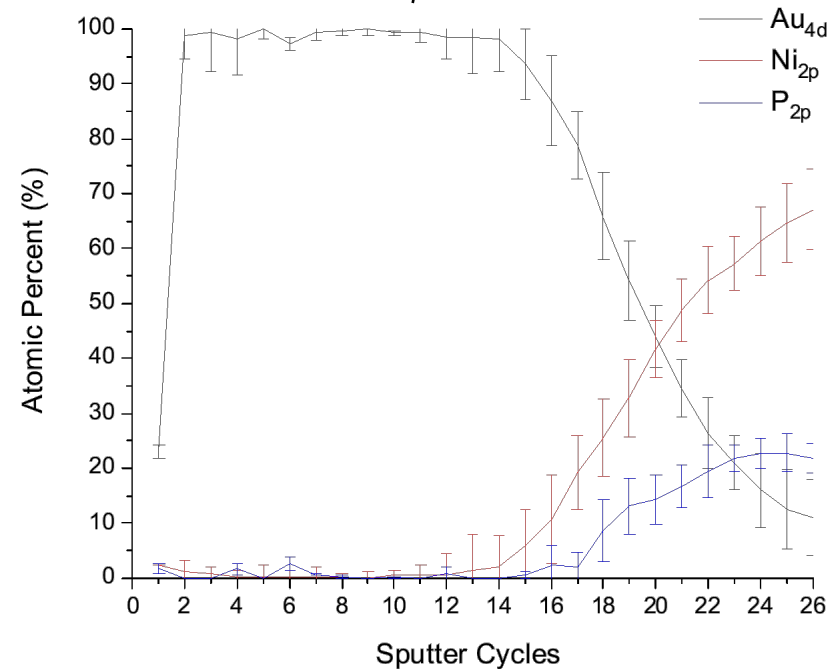


Sample Identifier (Vendor, Spot, Sputter Cycle)	Au 4f %	C 1s %	Cu 2p %	Ni 2p %	O 1s %	P 2p %
Vendor A 1.1	37.88	42.53	3.01	1.26	13.86	1.46
Vendor A 1.2	82.62	10.06	2.56	2.46	2.30	0.00
Vendor A 2.1	50.73	28.21	5.23	0.84	12.40	2.60
Vendor A 2.2	86.63	6.81	2.81	2.24	1.51	0.00
Vendor B 1.1	23.35	48.44	0.56	2.47	24.19	1.00
Vendor B 1.2	98.36	0.00	0.00	1.64	0.00	0.00
Vendor B 2.1	22.71	50.70	0.45	2.38	21.55	2.23
Vendor B 2.2	99.47	0.00	0.00	0.53	0.00	0.00

Results (X-Ray Photoelectron Spectroscopy Depth Profiling)



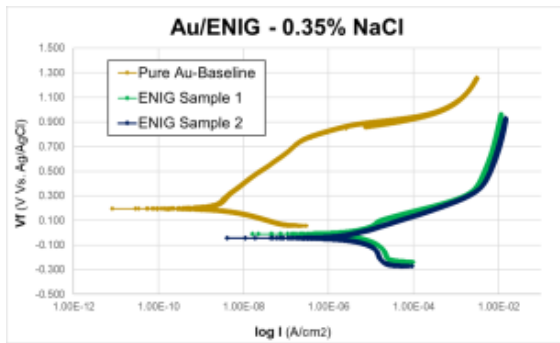
Osaka et. al. 2000
<https://doi.org/10.1149/1.1393313>



Putting It All Together

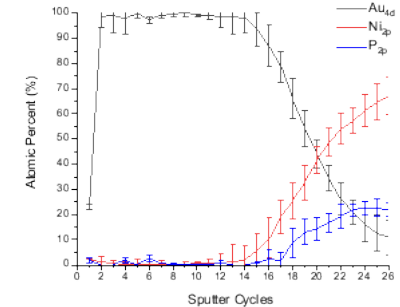
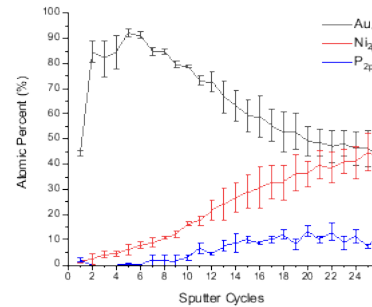


More Similar than Different

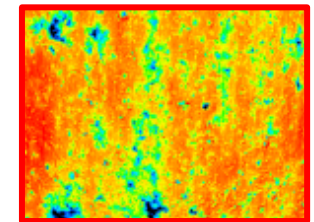
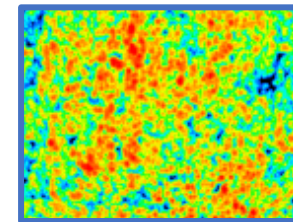
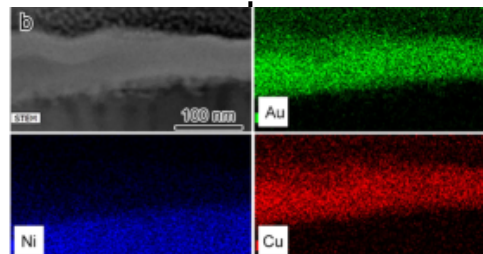
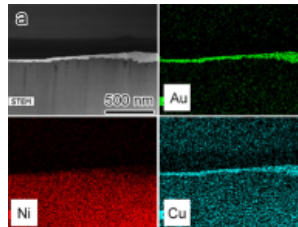


Vendor Samples Have Similar Passivity (or lack thereof)

More Different than Similar



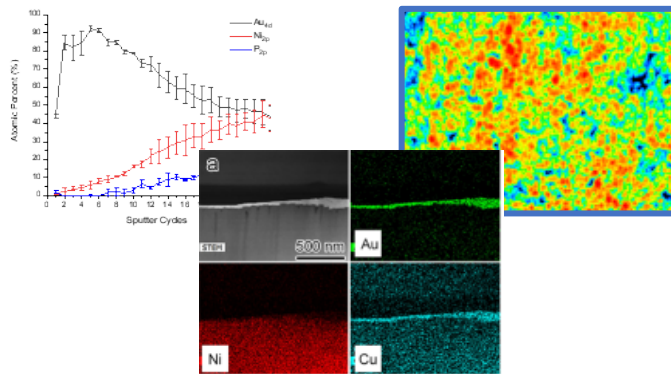
Vendor Samples Have Clearly Different Heterogeneity / Porosity



Vendor Samples Have Similar Morphological Defects and Contaminant Chemistry, Different Roughnesses

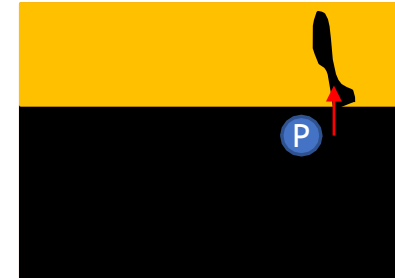
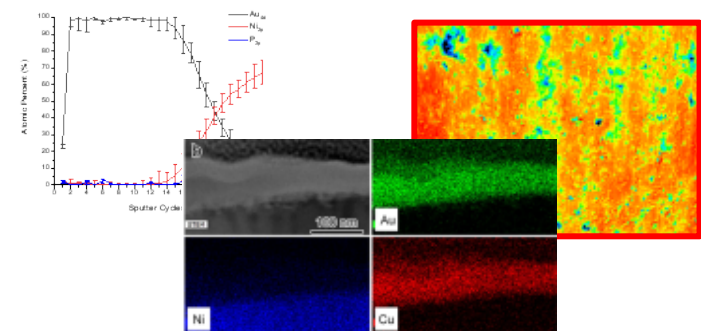


Vendor A



Poorly controlled plating conditions led to high Au porosity, susceptibility to Ni hyper corrosion in sol'n

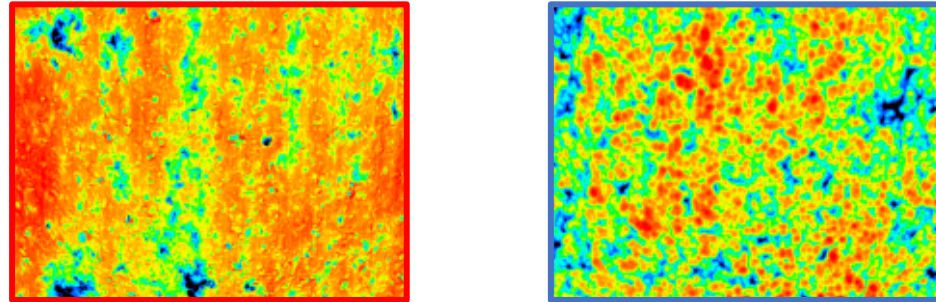
Vendor B



More ideal Au plating conditions, but choice of bath additives may have led to P-enrichment at Ni-Au interface, reducing film passivity

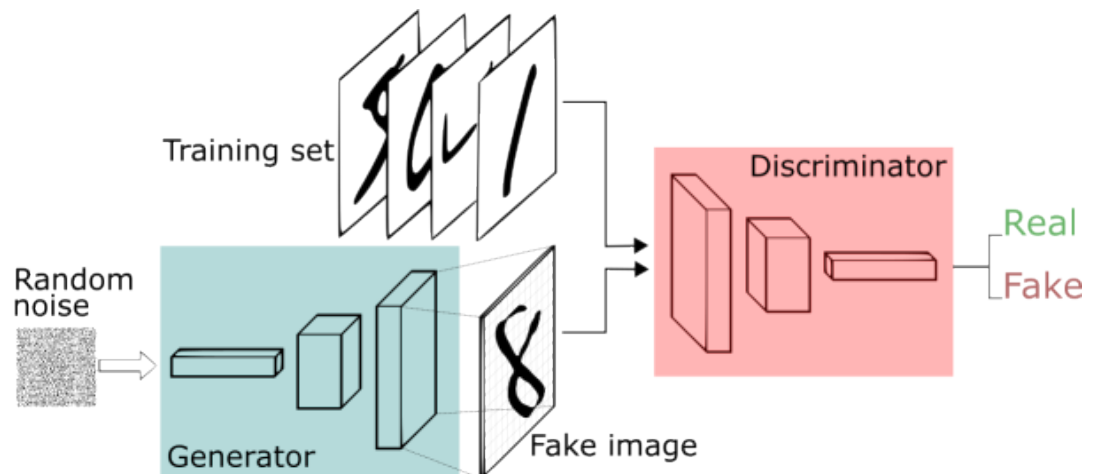


For classifying ‘good’ and ‘bad’... we need a much less comprehensive process



We can clearly see that the surface topology is encoding information about the SEM/TEM learned morphology, as well as the XPS learned ‘porosity’
Electrochemistry is likewise implied by these properties since the layers are sequential and conformal

These latent ‘fingerprints’ of the process-structure-property relationships could allow us to predict performance based on a training set of well characterized samples





Josh Kacher

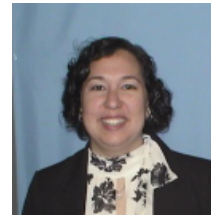
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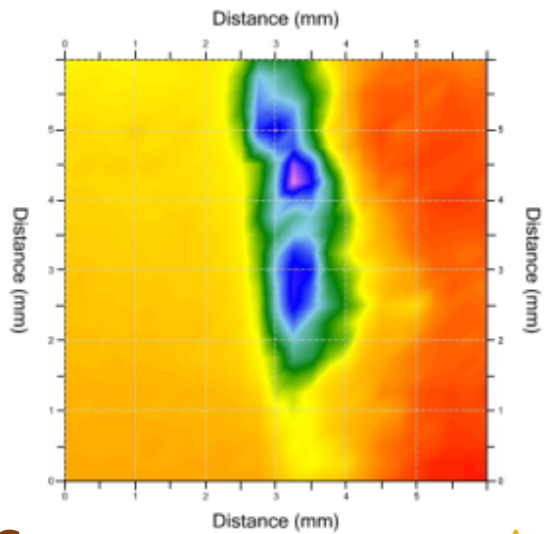
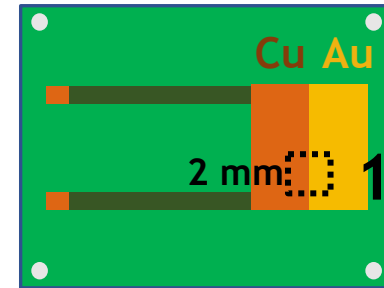
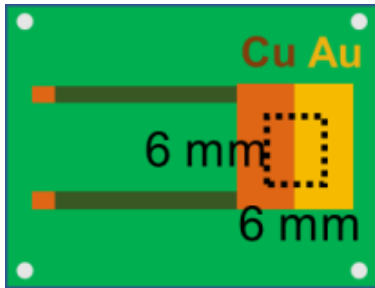
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Backup Slides

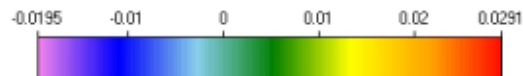


Results (Scanning Vibrating Electrode Technique)

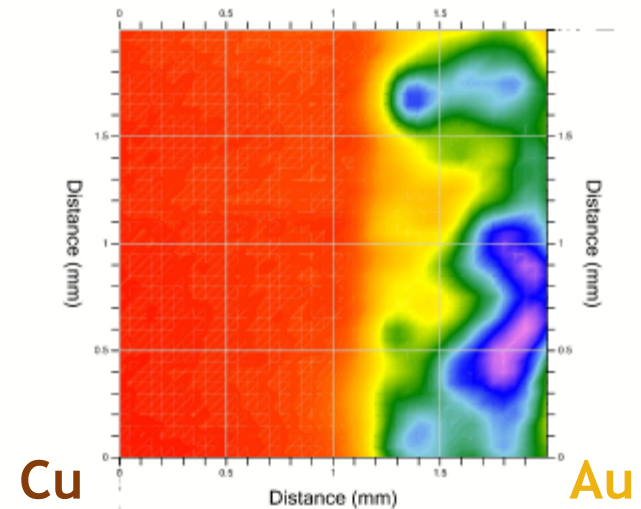


Cu

Au

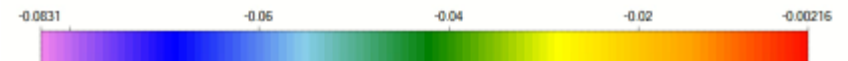


(in mV)



Cu

Au



(in mV)